

NOTES:

MATERIAL:

Housing: High Temperature Thermoplastic,UL 94V-0
Contacts:Phosphor bronze
Shell: Stainless Steel

PLATING:

Contacts: Plated 50 u" Ni Overall
Plated Au Selective Contact Area
Plated 100 u" Sn Over Ni On Solder Area

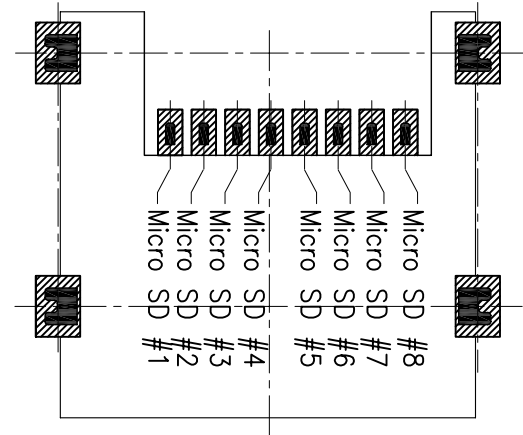
Electrical:

Current Rating :0.5mAmax.
Contact Resistance:100mΩmax
Insulation Resistance:1000MΩmin./500VDC
Dielectric Withstanding Voltage:500VAC/minute
Operating Temperature:-25°C TO+85°C
Mating Cycles:10,000 times

Usable Memory Card:

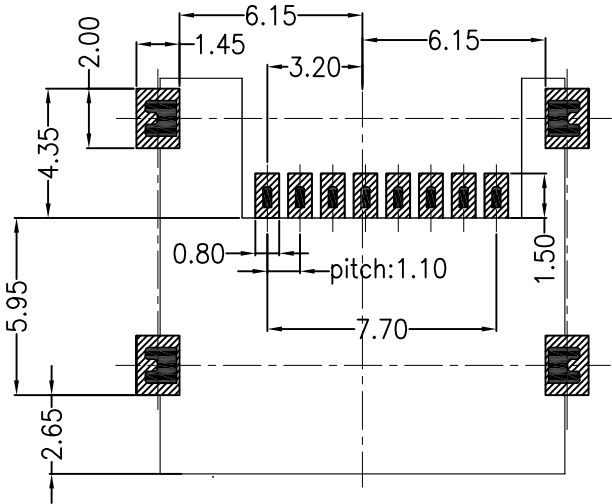
Micro SD Card

PIN ASSIGNMENT:



RECOMMEND PCB LAYOUT:

(Unit:mm .X ± 0.15 .XX ±0.05 .XXX ± 0.02)



Micro SD #1	Micro SD DAT2
Micro SD #2	Micro SD CD/DAT3
Micro SD #3	Micro SD CMD
Micro SD #4	Micro SD VDD
Micro SD #5	Micro SD CLK
Micro SD #6	Micro SD VSS
Micro SD #7	Micro SD DAT0
Micro SD #8	Micro SD DAT1



PART NO. TFC-WHCR-08

DWG NO. TFC-WHCR-08

FILE NO.

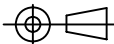
UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION



TOLERANCES ARE

.X ± 0.2

.XX ±

.XXX ±

AWG

DESCRIP TION:

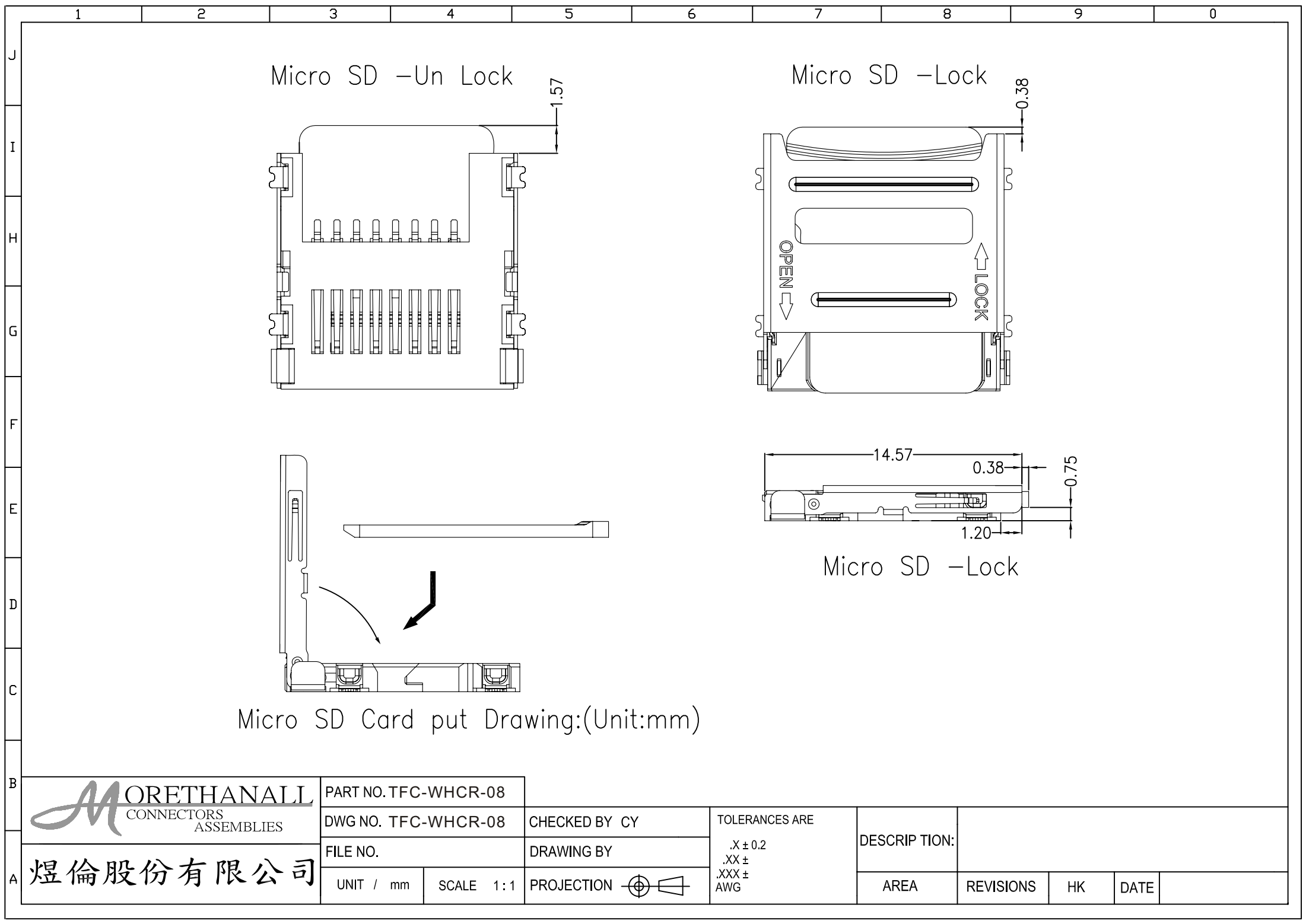
AREA

REVISIONS



HK

DATE

煜倫股份有限公司



Micro SD Card put Drawing:(Unit:mm)

<div></div> <div>煜倫股份有限公司</div>	PART NO. TFC-WHCR-08								
	DWG NO. TFC-WHCR-08		CHECKED BY CY	TOLERANCES ARE .X ± 0.2 .XX ± .XXX ± AWG	DESCRIP TION:				
	FILE NO.		DRAWING BY						
	UNIT / mm	SCALE 1:1	PROJECTION 		AREA	REVISIONS	HK	DATE	

